

1. PART NO. EXPRESSION :

P I C 0 8 0 3 H P 1 R 0 M F - □ □

(a) (b) (c) (d) (e) (f) (g)

(a) Series code

(b) Dimension code

(c) Type code

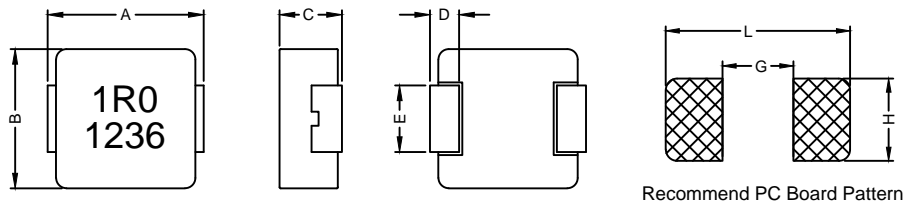
(d) Inductance code : 1R0 = 1.0uH

(e) Tolerance code : M = ±20%, Y = ±30%

(f) F : RoHS Compliant

(g) 11~99 : Internal control number

2. CONFIGURATION & DIMENSIONS :

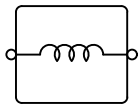


Recommend PC Board Pattern

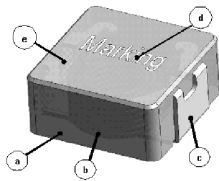
Unit:m/m

A	B	C	D	E	G	H	L
9.5±0.3	8.5±0.3	2.8±0.2	1.4±0.30	4.7±0.3	4.5	5.2	10.4

3. SCHEMATIC :



4. MATERIALS :



(a) Core

(b) Wire

(c) Terminal

(d) Ink

(e) Paint



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5. GENERAL SPECIFICATION :

- a) Test Freq. : L : 100KHz/1.0V
- b) Operating Temp. : -40°C to +125°C
- c) Storage Temp. : -40°C to +125°C
- d) Humidity Range : 85 ± 3% RH
- e) Heat Rated Current (Irms) will cause the coil temperature rise approximately Δt of 40°C (keep 1min)
- f) Saturation Current (Isat) will cause L0 to drop 20%.
- g) Part Temperature (Ambient+Temp. Rise) : Should not exceed 125°C under worst case operating conditions.
- h) Storage condition (component in its packaging)
 - i) Temperature: -10 to 40°C
 - ii) Humidity : 60%RH

6. ELECTRICAL CHARACTERISTICS :

Part No.	Inductance L ₀ (μH) @ 0 A	Irms (A) Typ.	Isat (A) Typ.	DCR (mΩ) Typ. @ 25°C	DCR (mΩ) Max. @ 25°C
PIC0803HPR22MF	0.22	30	45	1.46	1.61
PIC0803HPR33MF	0.33	25	37	2.3	2.6
PIC0803HPR47MF	0.47	21.5	35	3.0	3.4
PIC0803HP1R0MF	1.00	14	29	7.0	8.1
PIC0803HP1R5MF	1.50	11.5	24	10.2	11.8
PIC0803HP2R2MF	2.20	9	21	18	20.5
PIC0803HP3R3MF	3.30	8	14	23	27
PIC0803HP4R7MF	4.70	7	11	32	37
PIC0803HP6R8MF	6.80	5.5	9	46	53
PIC0803HP8R2MF	8.20	5	8.5	52	60
PIC0803HP100MF	10.0	4.7	8.2	65	75
PIC0803HP150MF	15.0	3.8	7	88	102

Tolerance code : M = ±20%, Y = ±30%



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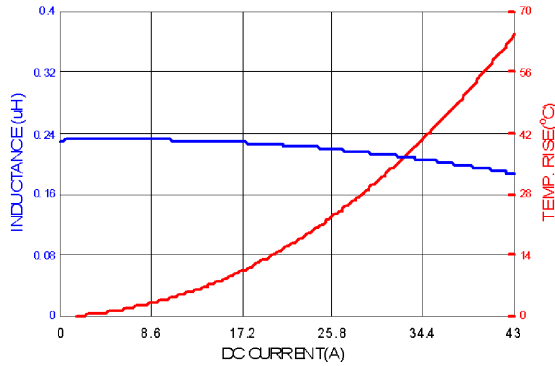
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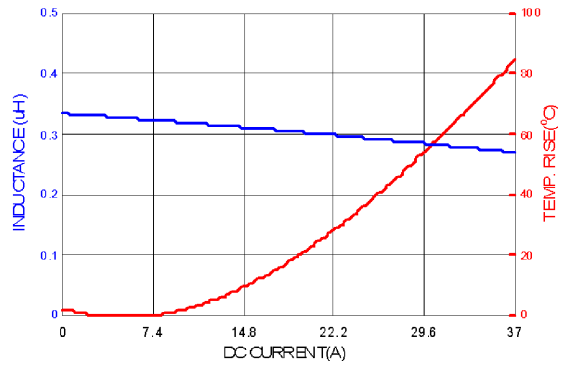
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7. CHARACTERISTICS CURVES :

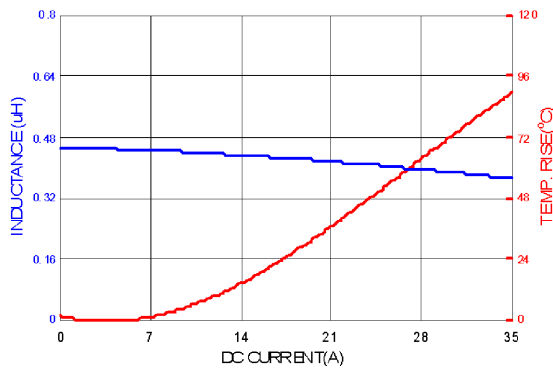
PIC0803HPR22MF



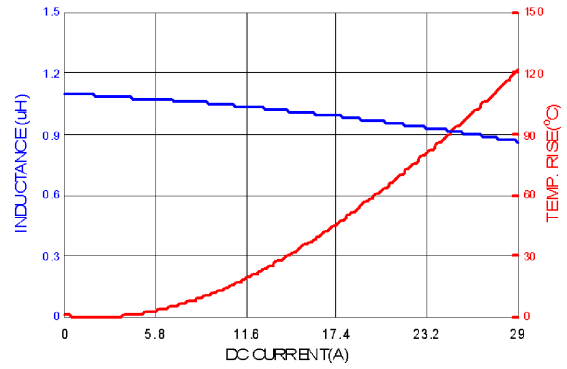
PIC0803HPR33MF



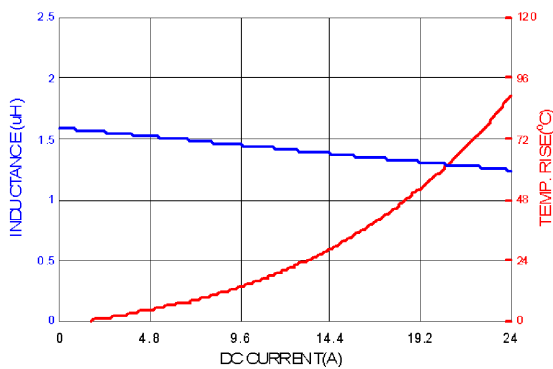
PIC0803HPR47MF



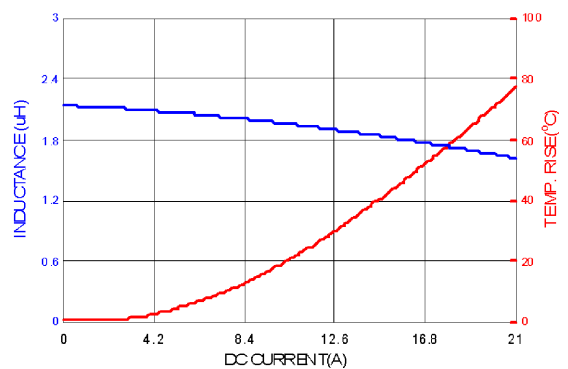
PIC0803HP1R0MF



PIC0803HP1R5MF



PIC0803HP2R2MF



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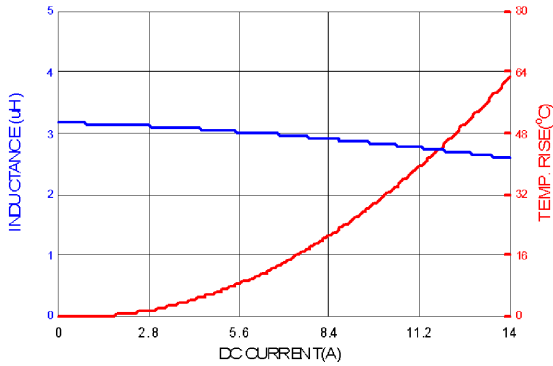
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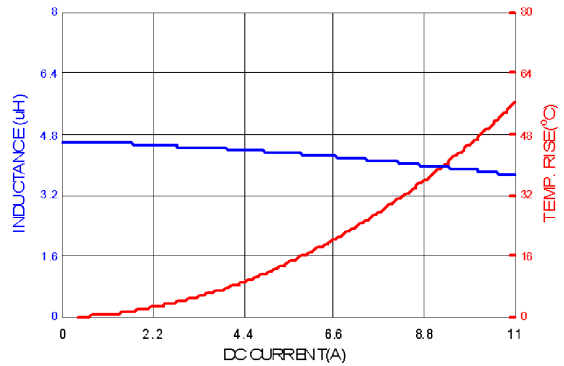


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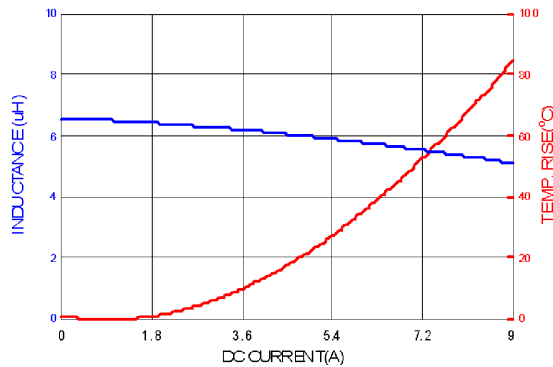
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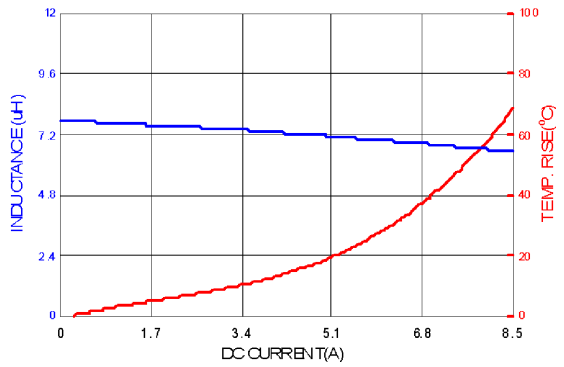
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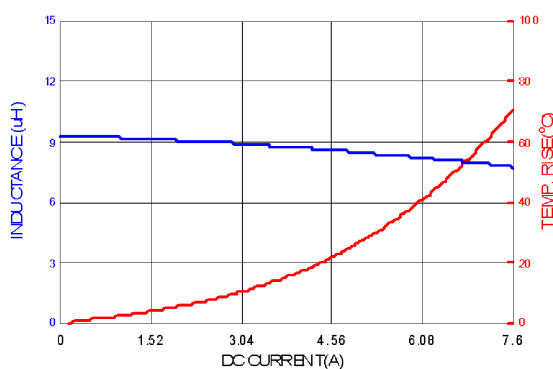
PIC0803HP6R8MF



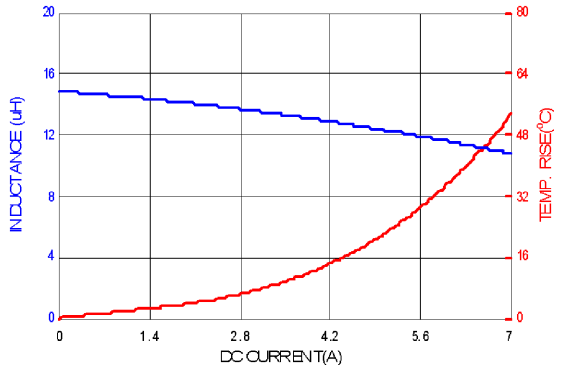
PIC0803HP8R2MF



PIC0803HP100MF



PIC0803HP150MF



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8. SOLDERING :

8-1. Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. Our terminations are suitable for all re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

8-1.1 Solder Re-flow :

Recommended temperature profiles for re-flow soldering in Figure 1.

8-1.2 Soldering Iron (Figure 2) :

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Note :

- a) Preheat circuit and products to 150°C.
- b) 355°C tip temperature (max)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (max)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4~5 secs.

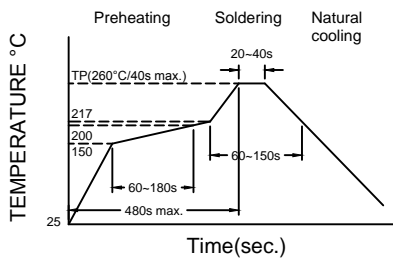


Figure 1. Re-flow Soldering: 3 times max.

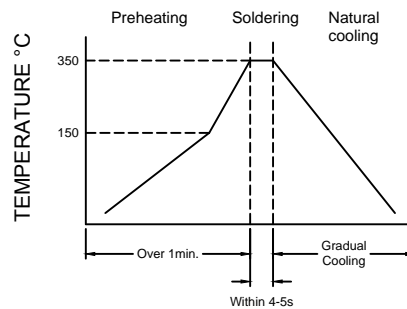


Figure 2. Iron Soldering: 1 times max.



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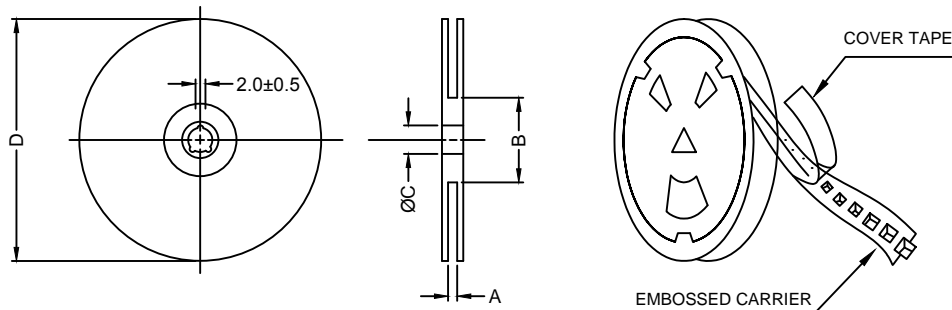
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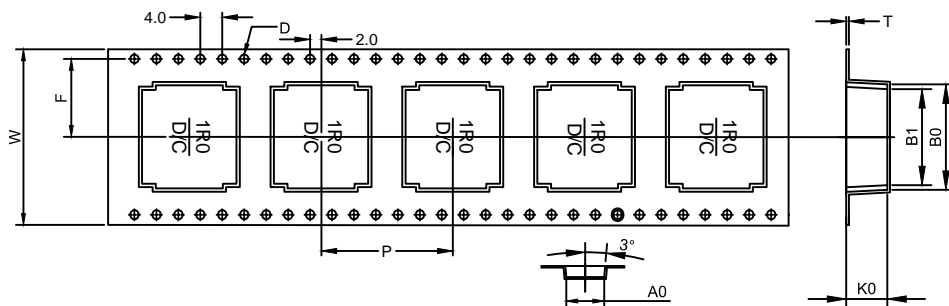
9. PACKAGING INFORMATION :

9-1. Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
13" x 24mm	24.4+2.0/-0	100±2	13.5±0.5	330

9-2 Tape Dimension



Series	Bo(mm)	B1(mm)	Ao(mm)	Ko(mm)	P(mm)	W(mm)	F(mm)	T(mm)	D(mm)
PIC0803	9.0±0.1	10.1±0.1	8.9±0.1	3.3±0.1	16.0±0.1	24±0.3	11.5±0.1	0.35±0.05	1.5±0.1

9-3. Packaging Quantity

Size	PIC0803
Chip / Reel	1000
Inner Box	2000
Carton	8000



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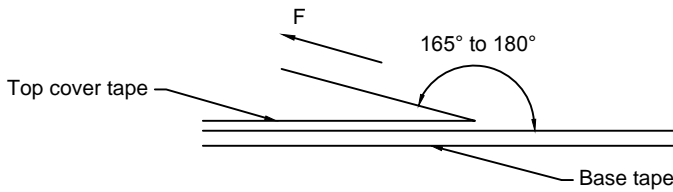
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9-4. Tearing Off Force



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions. (referenced ANSI/EIA-481-C-2003 of 4.11 standard)

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed (mm/min)
5~35	45~85	860~1060	300

Application Notice

1. Storage Conditions :

To maintain the solderability of terminal electrodes :

- a) Recommended products should be used within 12 months from the time of delivery.
- b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation :

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) Vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.



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